

VIGON® RC 303

Water-based cleaning medium for reflow and wave solder equipment



VIGON® RC 303 was specifically developed to remove all types of baked-on flux residues from reflow and wave solder equipment. It reliably removes re-condensed fluxes and emissions from assemblies. As the successor to VIGON® RC 101, VIGON® RC 303 delivers an improved cleaning performance with the same high level of operator safety.

Areas of application: Solder ovens		Additional product information :
Low solid flux residues*	++	Technical Information 3: Material compatibility overview. Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.
Rosin based flux residues*	++	
Water soluble flux residues*	++	
Synthetic fluxes*	++	
Fumigation contamination	++	

++ highly recommended, best results + recommended 0 possible - not recommended

* Valid for all standard-, lead-free and lead-based solders

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China Cleaning Process Solutions under Production Floor Conditions



Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:

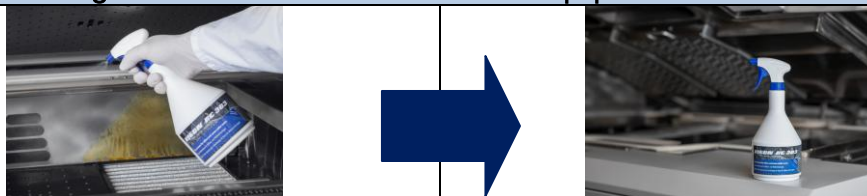
Phone: +49-841-635-26; Email: techsupport@zestron.com

Advantages compared to other cleaning agents:

- Higher cleaning quality and process reliability
 - Improved cleaning performance
 - The medium does not contain any ingredients which could leave residues on the oven surfaces. This avoids harmful condensation on the assembly surfaces after restarts.
 - Excellent material compatibility with aluminum and epoxy surfaces
- Mild formulation
 - No flash point
 - High operator safety
 - Environmentally friendly
 - No special labeling is required
 - Little odor
- More efficient cleaning process to avoid long machine downtimes
 - Short soaking time due to advanced formulation
 - Can be applied directly onto cold or warm surfaces (20 - 50 °C / 68 - 122 °F)
 - Also suitable for the pre-cleaning of condensation traps

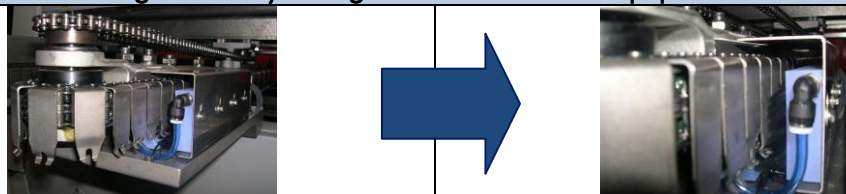
Typical Applications:

1) Manual cleaning of reflow ovens and wave solder equipment



1. Spray directly onto cold or warm surfaces (1l bottle).
2. Allow cleaning agent to stand for approximately 5 min.
3. Wipe surface clean with a cloth or paper towel.
4. Air dry

2) Automated cleaning of conveyor fingers in wave solder equipment



1. Fill VIGON® RC 303 into the cleaning reservoir of the wave solder equipment
2. Automatic brushing device in wave solder oven wipes clean conveyor fingers
3. Air dry

Technical Data

Density	(g/ccm) at 20°C/68°C	1,01
Surface tension	(mN/m) at 25°C/77°F	31,8
Boiling range	°C/°F	> 99/ > 210.2
Flash point	°C/°F	None
pH-value	10g/l H ₂ O	10.1
Vapor pressure	(mbar) at 20°C/68°F	Approx. 22
Cleaning temperature	°C/°F	20 – 50 / 68 – 122
Solubility in water		Soluble
Application concentration	Ready-to-use	Pure
HMIS Rating	Health/Flammability/Reactivity	0 – 0 – 0

PRODUCT FEATURES



Extensively tested and suitable for cleaning of lead-free solder pastes



Product is free of any critical substances according to SIN & SVHC lists



100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

Environmental, health and safety regulations:

- VIGON® RC 303 is water-based and biodegradable.
- VIGON® RC 303 is formulated free of halogenated compounds and is very environmentally friendly and considered a non-hazardous material.
- No special precaution for handling VIGON® RC 303 is required.

Availability/Storage:

- VIGON® RC 303 is available as a ready-to-use solution in 1l spray bottles, 5l or 25l containers and 200l drums.
- Store VIGON® RC 303 in the original container at a temperature between 5 - 30 °C / 41 - 86 °F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Alternative product recommendation:

- For dip-tank cleaning of removable oven parts, i.e. condensation traps or solder frames, we recommend ATRON® SP 200, ATRON® SP 300 or ATRON® SP 400.
- This also applies for extremely baked-on residues.